

LTM8029 35BGA 11.25mm X 6.25mm X 3.42mm (TABLE OF MATERIAL DECLARATION)

The LTM8029 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0756	Barium Compounds	7727-43-7	0.00197	2.61
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2, non-disclosure	0.01487	19.68
				Copper Metal	7440-50-8	0.04191	55.45
				Copper Compounds	147-14-8	0.00002	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.01
				Gold metal or alloy	7440-57-5	0.00011	0.15
				Nickel	7440-02-0	0.00054	0.71
				Zinc	7440-66-6	0.00008	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.01168	15.46
				Acrylic Resin	non-disclosure	0.00376	4.97
				Epoxy Resin	non-disclosure	0.00001	0.02
				Chromium(III) Oxide	1308-38-9	0.00000	0.00
				Silica Amorphous	7631-86-9	0.00004	0.06
				Talc;not containing fiber like asbestos	14807-96-6	0.00023	0.30
				Aromatic carbonyl compounds	non-disclosure	0.00021	0.28
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caobonate	471-34-1	0.00000	0.00
				Amine compounds	non-disclosure	0.00003	0.04
				Leveling agent and others	non-disclosure	0.00009	0.12
				2	Solder Paste	Alloy	0.0065
Sb	7440-36-0	0.00033	5.00				
3	Passive/Active Components		0.1163	Iron Powder (Fe)	7439-89-6	0.07563	65.03
				Copper (Cu)	7440-50-8	0.02489	21.41
				Nickel (Ni)	7440-02-0	0.00187	1.61
				Tin (Sn)	7440-31-5	0.00111	0.96
				Ceramic (Ba) Compounds	12047-27-7	0.01279	11.00
4	Active Ics	Silicon	0.0014	Silicon	7440-21-3	0.00136	100.00
5	Wire	Gold	0.0003	Au	7440-57-5	0.00033	99.99
6	Solder Ball	SAC305	0.0589	Sn	7440-31-5	0.05684	96.50
				Ag	7440-22-4	0.00177	3.00
				Cu	7440-50-8	0.00029	0.50
7	Encapsulation	Epoxy Resin	0.3023	Fused Silica	60676-86-0	0.23340	77.20
				Epoxy Resin	non-disclosure	0.02691	8.90
				Phenol Resin	non-disclosure	0.02691	8.90
				Crytalline Silica	14808-60-7	0.00907	3.00
				Carbon Black	1333-86-4	0.00151	0.50
				Metal Hydroxide	non-disclosure	0.00453	1.50
Total Package Weight			0.5613				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts